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ELECTRONIC ASSEMBLY, DESIGN AND CIRCUIT BOARDS – VOCABULARY –

Part 2: Common usage in electronic technologies as well as electronic assembly technologies

FOREWORD

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IEC 60194-2 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This second edition cancels and replaces the first edition published in 2017. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) exclusion of 116 terms transferred to IEV;
b) inclusion of 9 new terms related to printed electronics and packaging technology;
c) revision of definitions of 23 terms reflecting current technology;

d) three "printed wiring" terms were removed;

e) reintroduction of identification codes for terms.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1996/FDIS	91/2014/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 60194 series, published under the general title *Electronic assembly, design and circuit boards*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

ELECTRONIC ASSEMBLY, DESIGN AND CIRCUIT BOARDS – VOCABULARY –

Part 2: Common usage in electronic technologies as well as electronic assembly technologies

1 Scope

This part of IEC 60194 covers terms and definitions related to circuit board and electronic assembly technologies as well as other electronic technologies.

The terms have been classified according to the decimal classification code (DCC) and this DCC number appears just below the defined term. The DCC numbering is fully explained in Annex A.

A list of terms in alphabetical order with code number is provided in Annex B.

2 Normative references

There are no normative references in this document.